



OLCC

Organic Land Chip Carrier Package

DESCRIPTION

LINGSEN's Organic Land Chip Carrier (OLCC) package is an AR glass- capped package of BT substrate. With AR-glass, OLCC provides the excellent transmittance for the lighting and optical sensor device of the visible application. The leads of OLCC are located around the bottom periphery of the package to provide short electrical connection to the PWB.

APPLICATIONS

- Storage products:
- DVD Reader
Blue Ray DVD reader
- Optical products:
CMOS camera

SPECIFICATIONS

- Substrate: BT, thickness= 1.01 mm
- Gold Wire: 99.99%Au
- Glass: AR Glass. AR film deposited on one or both sides.
- Transmittance: Average>99% @ wavelength=400~700nm
- Lead: Au Plated Foot Print
- Marking: White Ink
- Packing: Tube

DEFINITION

OLCC (Organic Land Chip Carrier package):

An AR glass-capped package of BT substrate.

The excellent transmittance for the lighting and optical sensor device of the visible application.

Package thickness is 1.31mm.

RELIABILITY

MSL Level JEDEC Level 4@ 245°C

FEATURES

- AR Glass
- Visible and IR Application
- BT Substrate
- Full In-House Design Capability

THERMAL PERFORMANCE

Package	Body Size (mm)	Die Size (mm)	Thermal Performance θ_{ja} (°C/W)
OLCC 38L	6x6	3.4x2.9	40.43

Note: Simulated with JEDEC Standard 4-layer test board and 51-series under still air condition, ambient temperature 45°C

ELECTRICAL PERFORMANCE

Package	Body Size (mm)	Frequency (MHz)	Self Inductance (nH)	Self Capacitance (pF)	Resistance (mohm)
OLCC 38L	6x6	100	0.353~3.597	0.357~5.933	13.647~113.470

Note: Results are simulated. Data is available through 1GHz. Follow JEDEC standard 51-series.

CROSS-SECTION

